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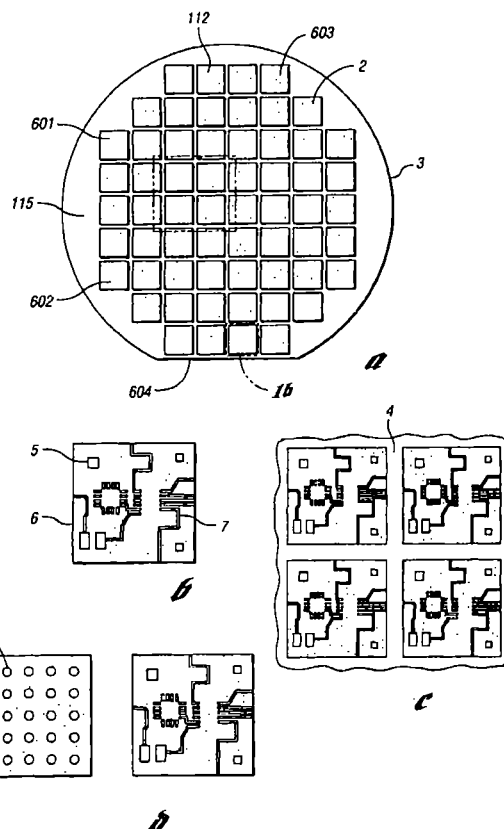
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(54) Title: METHOD AND SYSTEM FOR MARKING A WORKPIECE SUCH AS A SEMICONDUCTOR WAFER AND LASER MARKER FOR USE THEREIN



(57) Abstract: A system for semiconductor wafer (3) marking is provided. The system includes: (a) a first positioning subsystem for positioning a laser marking field relative to a wafer, the positioning along a first direction; (b) an alignment vision subsystem; (c) a laser marker including a laser for marking a location within the marking field with a laser marking beam; (d) a calibration program for calibrating at least one subsystem of the system; and (e) a controller. The marking field is substantially smaller than the wafer, and the laser marker includes a scan lens for optically maintaining a spot formed by the beam on the wafer within an acceptable range about the location within the marking field so as to avoid undesirable mark variations associated with wafer sag or other variations in depth within the field.

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ACTION

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Declarations under Rule 4.17:

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- *as to the applicant's entitlement to claim the priority of the earlier application (Rule 4.17(iii)) for the following designations* AE, AG, AL, AM, AT, AU, AZ, BA, BB, BG, BR, BY, BZ, CA, CH, CN, CO, CR, CU, CZ, DE, DK, DM, DZ, EC, EE, ES, FI, GB, GD, GE, GH, GM, HR, HU, ID, IL, IN, IS, JP, KE, KG, KP, KR, KZ, LC, LK, LR, LS, LT, LU, LV, MA, MD, MG, MK, MN, MW, MX, MZ, NI, NO, NZ, OM, PH, PL, PT, RO, RU, SC, SD, SE, SG, SK, SL, TJ, TM, TN, TR, TT, TZ, UA, UG, UZ, VC, VN, YU, ZA, ZM, ZW, ARIPO patent (GH, GM, KE, LS, MW, MZ, SD, SL, SZ, TZ, UG, ZM, ZW), Eurasian patent (AM, AZ, BY, KG, KZ, MD, RU, TJ, TM), European patent (AT, BE, BG, CH, CY, CZ, DE, DK, EE, ES, FI, FR, GB, GR, HU, IE, IT, LU, MC, NL, PT, RO, SE, SI, SK, TR), OAPI patent (BF, BJ, CF, CG, CI, CM, GA, GN, GQ, GW, ML, MR, NE, SN, TD, TG)
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